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**UPDATE CHANGE NOTIFICATION # 16710**Generic Copy

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**Issue Date:** 16-Sep-2011**TITLE:** Copper wire bond for Micro 8 package in Seremban, Malaysia**PROPOSED FIRST SHIP DATE:** 05-Dec-2011**AFFECTED CHANGE CATEGORY(S):** Assembly Process**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Tomas Vajter<[tomas.vajter@onsemi.com](mailto:tomas.vajter@onsemi.com)>**SAMPLES:** Contact your local ON Semiconductor Sales Office or Ahmad Taufek Md Noah  
<[ahmad.taufek@onsemi.com](mailto:ahmad.taufek@onsemi.com)>**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Alan Garlington<[alan.garlington@onsemi.com](mailto:alan.garlington@onsemi.com)>**NOTIFICATION TYPE:**ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.**DESCRIPTION AND PURPOSE:**

A General Announcement (GA#16200) was published on 1-29-09 regarding the ongoing Copper Wire bond conversion program at ON Semiconductor. This is a FPCN to notify customers of its plan to qualify Copper Wire (in place of Gold Wire) on the Micro 8 packages assembled at the Seremban, Malaysia assembly location. Reliability Qualification and full electrical characterization over temperature has now been completed on the designated package qualification vehicles.

This update notice is to add one additional part number to the list of parts affected by the FPCN 16710 issued on 1 Sept 2011. The part number was accidentally missed in the original FPCN.

Please see FPCN # 16710 for information on Reliability Data and Changed Part identification.

**List of affected General Parts:**

NCV33161DMR2G